Date: Dec.27,2013

RENESAS TECHNICAL UPDATE

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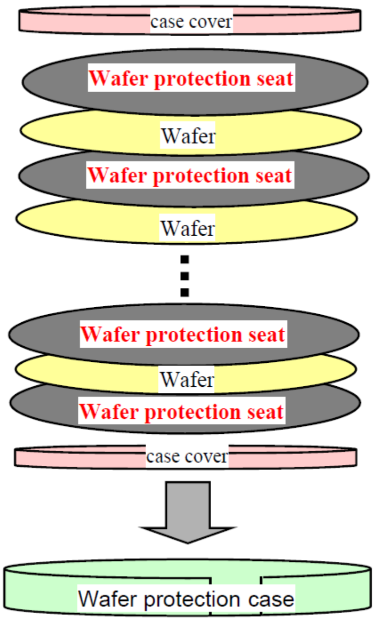
Renesas Electronics Corporation

Product Category	Standard Logic IC		Document No.	TN-WLG-A001A/E	Rev.	1.00
Title	The change of tray packing wafer protection seat for wafer delivery products		Information Category	Technical Notification		
Applicable Product	Standard Logic IC	Lot No. Since May, 2014	Reference Document	Nothing		

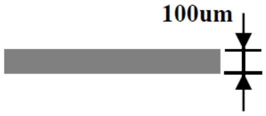
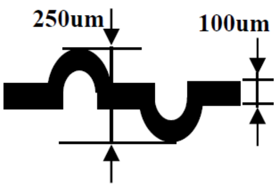
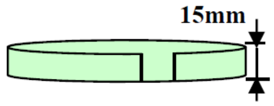
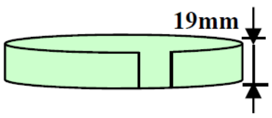
1.The reason for the change: For the material maker manufacturing discontinuance.
2.Content of change: Please refer to the following. The height of the wafer protection case changes along with the change of this wafer protection seat thickness.
3.This change is applied from the production in May 2014.
4.Product features etc. : There is no change of the electrical specification and reliability, etc. by this change.

Content of change The wafer protection seat and the wafer protection case are changed.



Wafer delivery products tray packing outline chart

The comparison table of before and after the change.

		Before change	After change
Wafer Protection seat	Front elevation	 Gray (Electroconductive olefine resin)	 Black (Carbon polyethylene)
	Cross section	(Non Emboss) 	(Emboss) 
Wafer Protection case	Height		

5. Applicable Products.(P/N)

RD74LVC08BWAW0、RD74LVC125BWAW0、RD74LVC240BWAW0
HC151TS303BSTW、HC151TS304BSTW、HC151TS305BSTW、HC151TS315BSTW
HC74ALVC2G66W
RD151TS3401BWAW0
HC74HC02RW、HA74HC04RW、HC74HC08RW、HC74HC4053W
HC74LS00RW、HC74LS04RW、HC74LS07W、HC74LS08RW、HC74LS125AYW、HC74LS14RW、
HC74LS27RW、HC74LS73AW